Infineon Technologies
Packaging Center Regensburg-Burgweinting
Key Facts

Lead fab for technology, innovation and marketing
Development and volume production of modules for chip card applications

Since 1990: assembly of chip card modules in Regensburg
August 2000: new production site in Regensburg-Burgweinting

Total area: 2,500 m²
Production volume: 670 million modules in FY 2003/04 (in total 3 billion modules by July 2004)
Employees: 260 (total employees at site Regensburg: approx. 2,800)
Products and Technologies: chip card modules in wirebond and FCOS™ technology, contactless modules in mold and flip chip technology, RFID inlays
Pre-assembly: wafer thinning, dicing, bumping

The packaging center Regensburg-Burgweinting, together with its Chinese plant in Wuxi, is worldwide market leader for chip card modules.